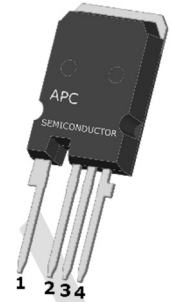
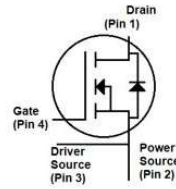




SiC Power MOSFET with Ceramic Isolated Baseplate Tab

AMR020V120H2i



Applications:

- Solar Inverters
- Uninterrupted power supplies
- Switch mode power supplies
- Motor drives

Features:

- High blocking voltage with low on-resistance
- High switching speed with low capacitance
- Very low switching losses
- Excellent avalanche ruggedness
- Very fast and robust intrinsic body diode with low reverse recovery
- 0V turn-off V_{gs} for gate driving ease
- RoHS compliant

Absolute Maximum Ratings ($T_{amb}=25^{\circ}C$, unless specified otherwise)

Symbol	Parameter	Value	Unit
V_{DS}	DC Reverse Voltage	1200	V
V_{GSmax}	Gate-source voltage, max. transient voltage	-10/+25	
V_{GSmax}	Gate-source voltage, max. static voltage	-8/+22	
V_{GSop}	Gate-source voltage	-5/+18	
I_D	Continuous drain current ($V_{GS} = 18V$)	88	A
	Continuous drain current ($V_{GS} = 18V$), $T_C = 100^{\circ}C$	62	
$I_{D(pulse)}$	Pulsed drain current (Pulse width limited by T_{jmax})	220	A
P_{tot}	Power dissipation	403	W
T_j	Operating junction temperature	-55 to 175	$^{\circ}C$
T_{stg}	Storage temperature	-55 to 175	$^{\circ}C$

Thermal and Mechanical Characteristics

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
$R_{\theta JC}$	Junction-to-case thermal Resistance		-	TBD	-	$^{\circ}C/W$

Static Electrical Characteristics ($T_A = 25^\circ\text{C}$, unless specified otherwise)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 100\mu A$	1200	-	-	V
$V_{GS(th)}$	Gate-Source Threshold Voltage	$V_{DS} = V_{GS}, I_D = 18mA^a$	1.8	3.2	4.2	
		$V_{DS} = V_{GS}, I_D = 18mA,$ $T_j = 175^\circ\text{C}^a$	-	2.4	-	
I_{DSS}	Drain-Source Leakage current	$V_{DS} = 1200V, V_{GS} = 0V$	-	1	150	μA
I_{GSS}	Gate-Source leakage current	$-10V < V_{GS} < 25V$	-	1	100	nA
$R_{DS(on)}$	Drain-Source ON Resistance	$V_{GS} = 15V, I_D = 40A$	-	23	-	m Ω
		$V_{GS} = 18V, I_D = 40A$	-	20	26	
		$V_{GS} = 18V, I_D = 40A,$ $T_j = 175^\circ\text{C}$	-	32	-	
g_{fs}	Transconductance	$V_{DS} = 20V, I_D = 40A$	-	26	-	S
		$V_{DS} = 20V, I_D = 40A,$ $T_j = 175^\circ\text{C}$	-	27	-	
$R_{g(int)}$	Internal gate resistance	$f = 1MHz, V_{AC} = 25mV$	-	2.9	-	Ω

^a Pre-condition V_{th} , as per JEDEC standard JEP183A, (Revision of JEP183 January 2021)

Dynamic Characteristics ($T_A = 25^\circ\text{C}$, unless specified otherwise)

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
C_{iss}	Input Capacitance	$V_{GS} = 0V, V_{DS} = 1000V,$ $f = 100kHz, V_{AC} = 25mV$	-	3533	-	pF
C_{oss}	Output Capacitance		-	147	-	
C_{rss}	Reverse Transfer Capacitance		-	9	-	
E_{oss}	C_{oss} stored energy		-	84	-	μJ
Q_{gs}	Gate-Source Gate Charge	$V_{DD} = 800V, V_{GS} = -5/+18V,$ $I_D = 40A, I_{GS} = 1mA$	-	50	-	nC
Q_{gd}	Gate-Drain Gate Charge		-	40	-	
Q_g	Total Gate Charge		-	154	-	

Switching Characteristics ($T_A = 25^\circ\text{C}$, unless specified otherwise)

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
$T_{d(on)}$	Turn-on delay time	$V_{DD} = 800\text{V}$, $V_{GS} = -5/+18\text{V}^b$, $I_D = 40\text{A}$, $R_{G(ext)} = 2.4\Omega$, $L = 110\mu\text{H}$	-	18	-	ns
T_r	Rise time		-	22	-	
$T_{d(off)}$	Turn-off delay time		-	41	-	
T_f	Fall time		-	12	-	
E_{on}	Turn On Switching Energy		-	532	-	μJ
E_{off}	Turn Off Switching Energy		-	46	-	
$T_{d(on)}$	Turn-on delay time	$V_{DD} = 800\text{V}$, $V_{GS} = -5/+18\text{V}^b$, $I_D = 40\text{A}$, $R_{G(ext)} = 2.4\Omega$, $L = 110\mu\text{H}$, $T_j = 175^\circ\text{C}$	-	16	-	ns
T_r	Rise time		-	26	-	
$T_{d(off)}$	Turn-off delay time		-	52	-	
T_f	Fall time		-	13	-	
E_{on}	Turn On Switching Energy		-	749	-	μJ
E_{off}	Turn Off Switching Energy		-	53	-	

^b This SIC MOSFET can switch with driver pulses 0V to 20V with optimized PCB layouts and gate drive circuits.

Body Diode Characteristics ($T_A = 25^\circ\text{C}$, unless specified otherwise)

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
V_{SD}	Body Diode Forward Voltage	$V_{GS} = -5\text{V}$, $I_{SD} = 40\text{A}$	-	4.1	-	V
		$V_{GS} = -5\text{V}$, $I_{SD} = 40\text{A}$, $T_j = 175^\circ\text{C}$	-	3.6	-	
I_S	Continuous diode forward current	$T_C = 25^\circ\text{C}$	-	-	88	A
$I_{S,pulse}$	Diode pulse current	$V_{GS} = -5\text{V}$, pulse width t_p limited by T_{jmax}	-	-	220	A
t_{rr}	Reverse recovery time	$V_{GS} = -5\text{V}$, $I_{SD} = 40\text{A}$, $V_R = 800\text{V}$, $di_f/dt = 2.98\text{kA}/\mu\text{s}$	-	15	-	ns
Q_{rr}	Reverse recovery charge		-	0.37	-	μC
I_{rrm}	Peak reverse recovery current		-	42	-	A
t_{rr}	Reverse recovery time	$V_{GS} = -5\text{V}$, $I_{SD} = 40\text{A}$, $V_R = 800\text{V}$, $T_j = 175^\circ\text{C}$, $di_f/dt = 3.12\text{kA}/\mu\text{s}$	-	26	-	ns
Q_{rr}	Reverse recovery charge		-	1.02	-	μC
I_{rrm}	Peak reverse recovery current		-	63	-	A

Electrical Characteristic Diagrams

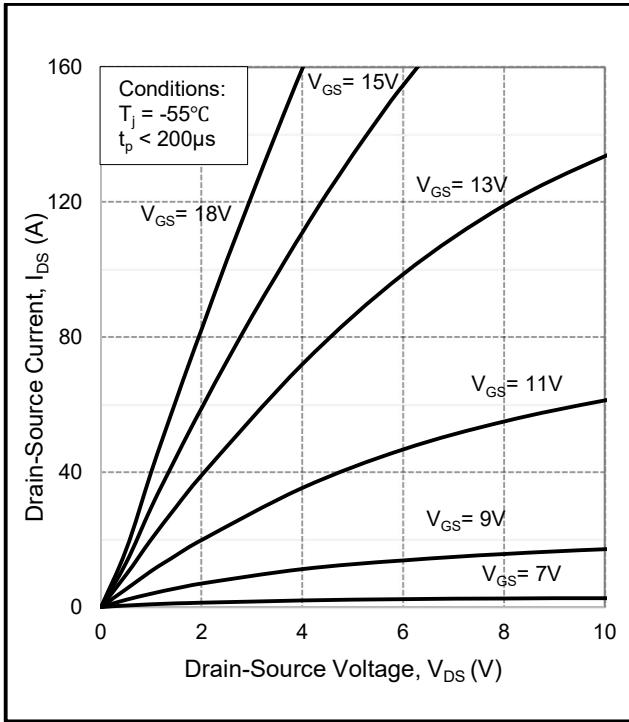


Figure 1. Output characteristics at $T_j = -55^\circ\text{C}$

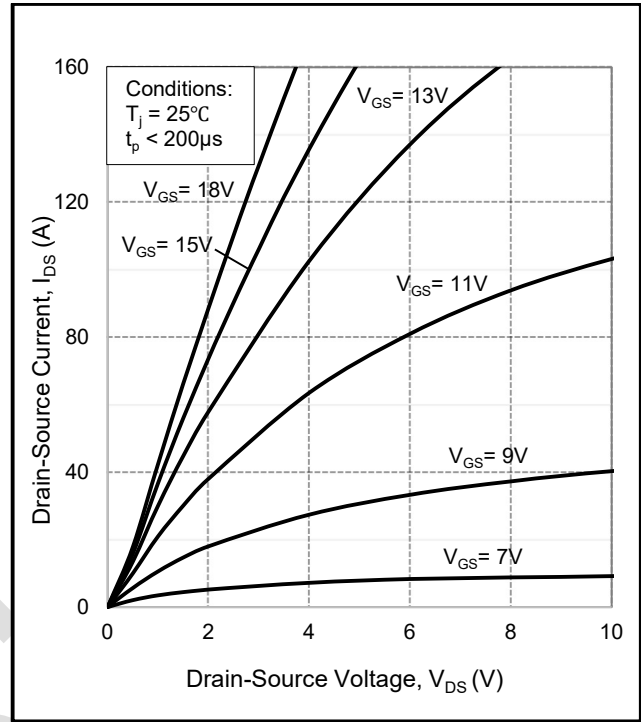


Figure 2. Output characteristics at $T_j = 25^\circ\text{C}$

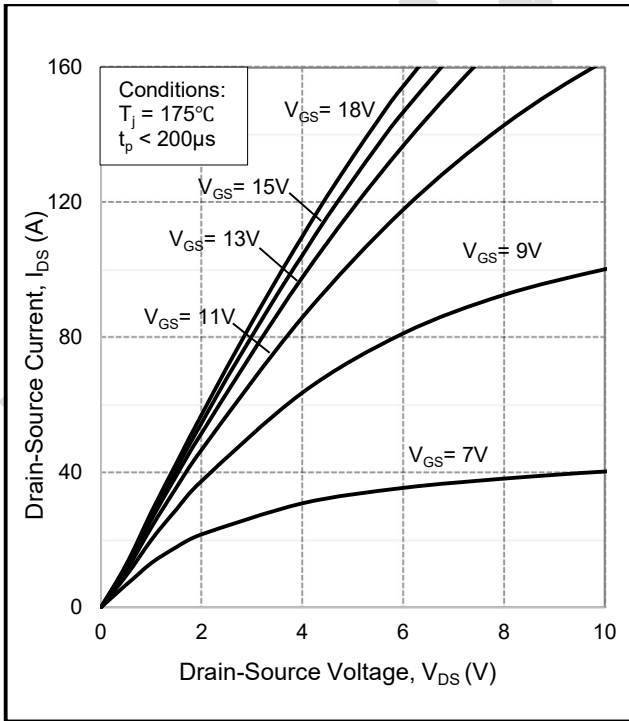


Figure 3. Output characteristics at $T_j = 175^\circ\text{C}$

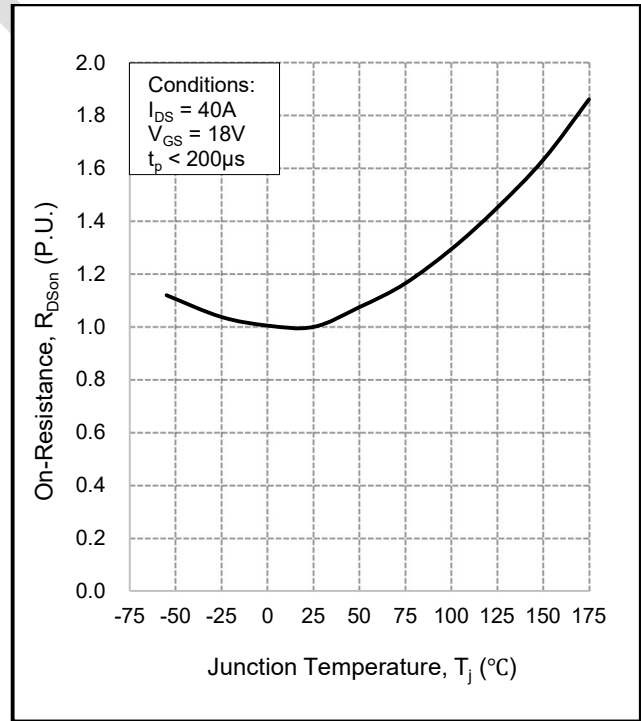


Figure 4. Normalized on-resistance vs. temperature

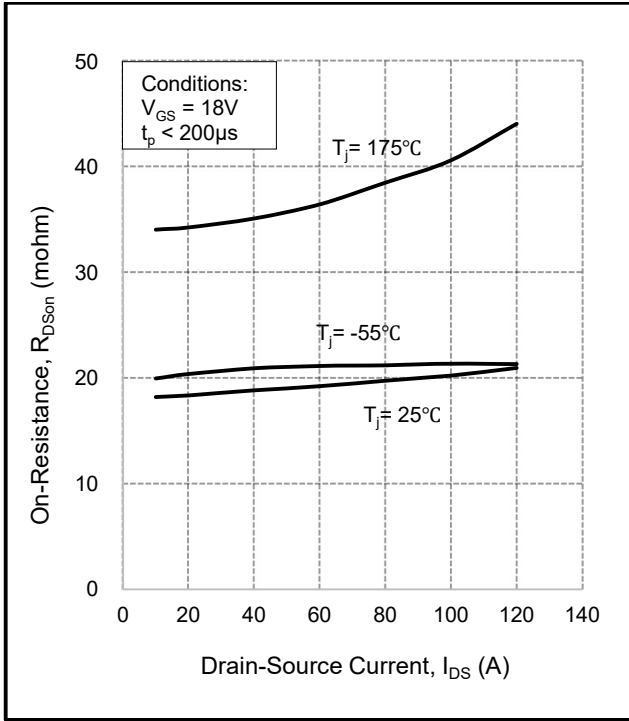


Figure 5. On-resistance vs. drain current for various temperatures

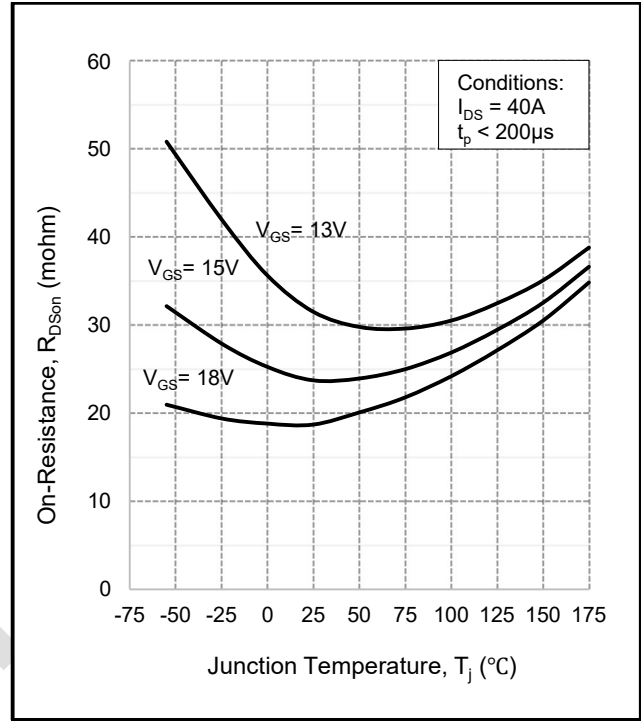


Figure 6. On-resistance vs. temperature for various gate voltages

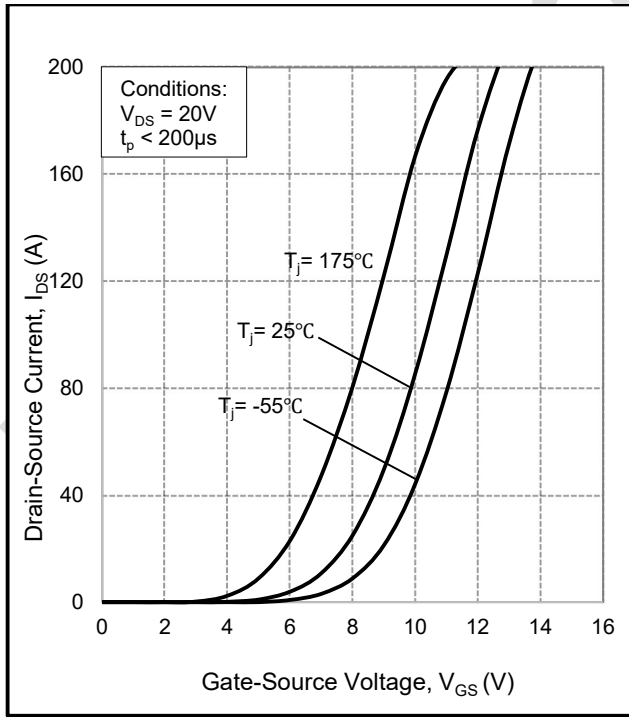


Figure 7. Transfer characteristic for various junction temperatures

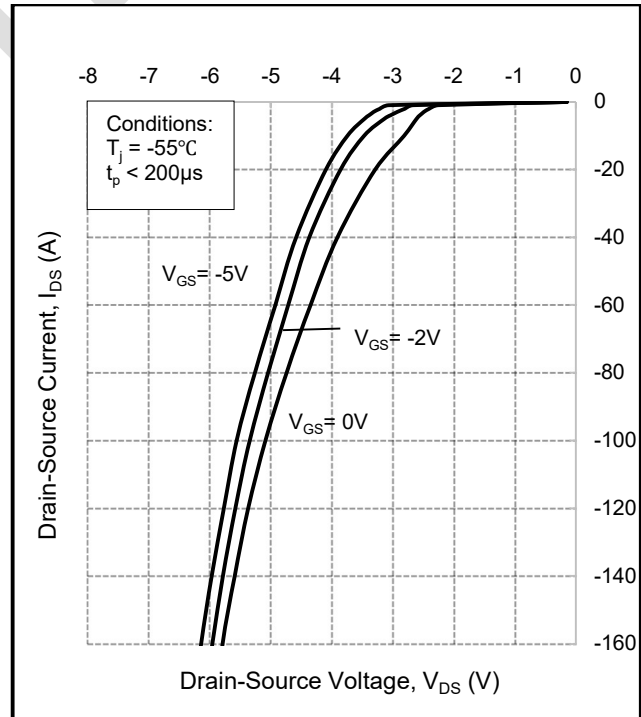


Figure 8. Body diode characteristic at $T_J = -55^\circ\text{C}$

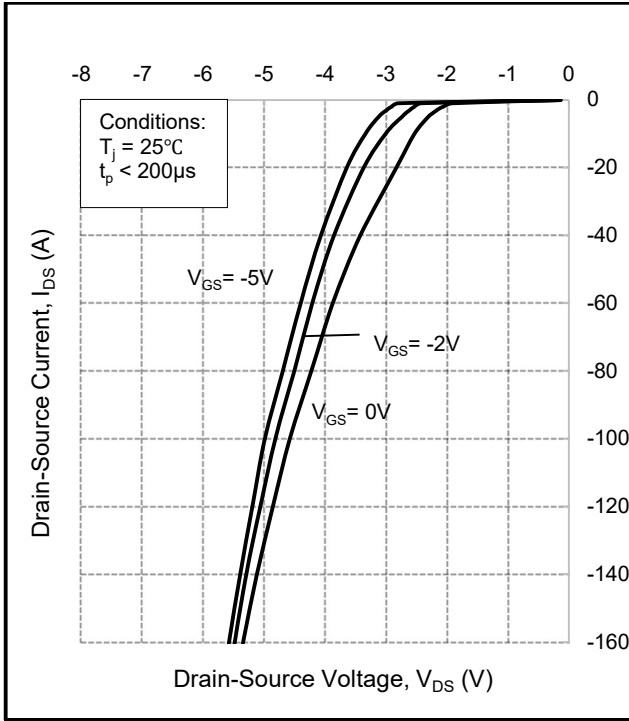


Figure 9. Body diode characteristic at $T_j = 25^\circ\text{C}$

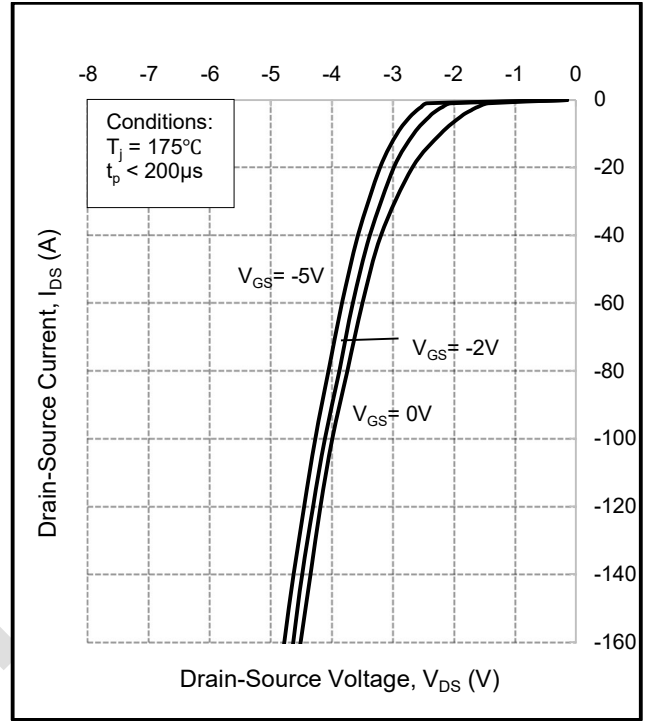


Figure 10. Body diode characteristic at $T_j = 175^\circ\text{C}$

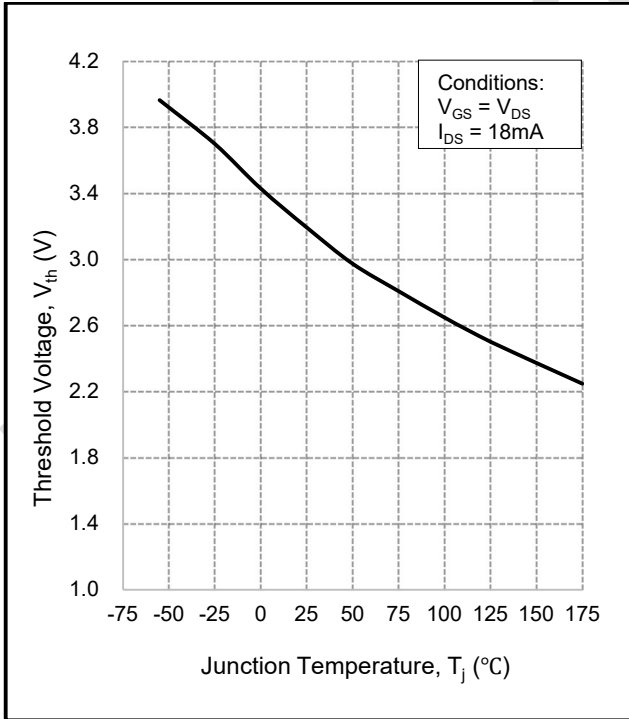


Figure 11. Threshold voltage vs. temperature

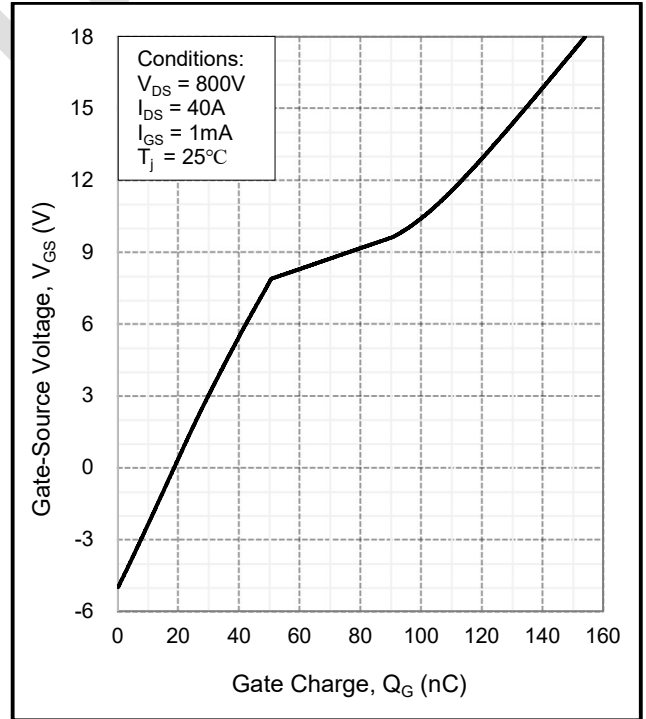


Figure 12. Gate charge characteristics

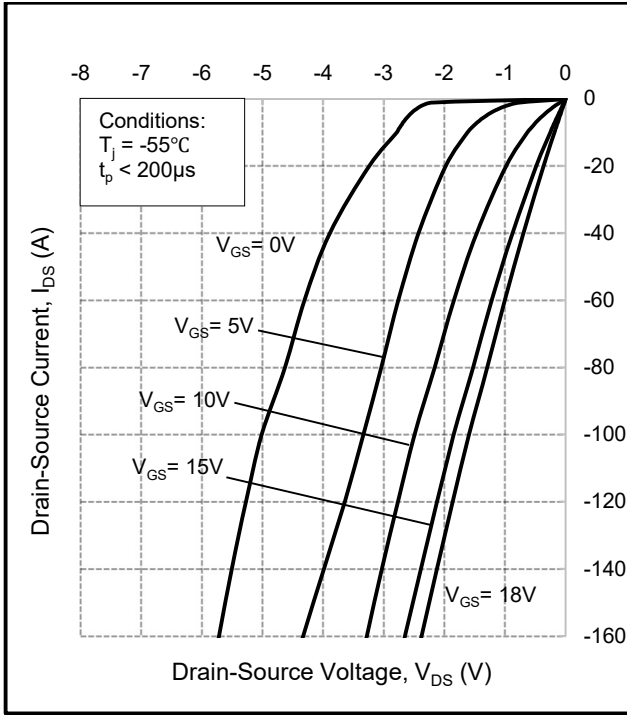


Figure 13. 3rd quadrant characteristic at $T_j = -55^\circ\text{C}$

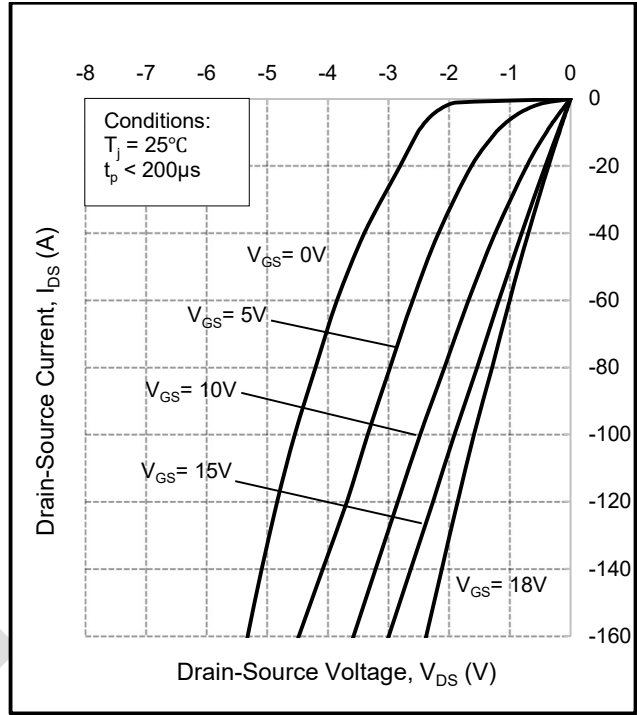


Figure 14. 3rd quadrant characteristic at $T_j = 25^\circ\text{C}$

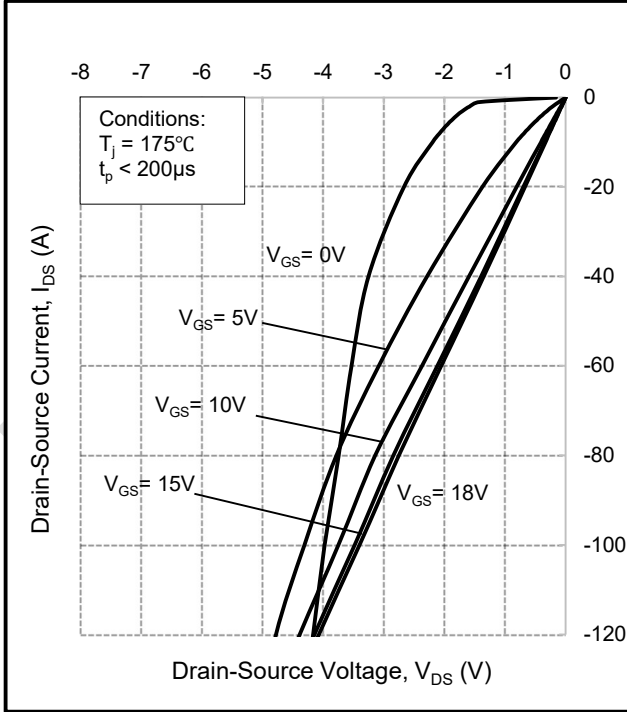


Figure 15. 3rd quadrant characteristic at $T_j = 175^\circ\text{C}$

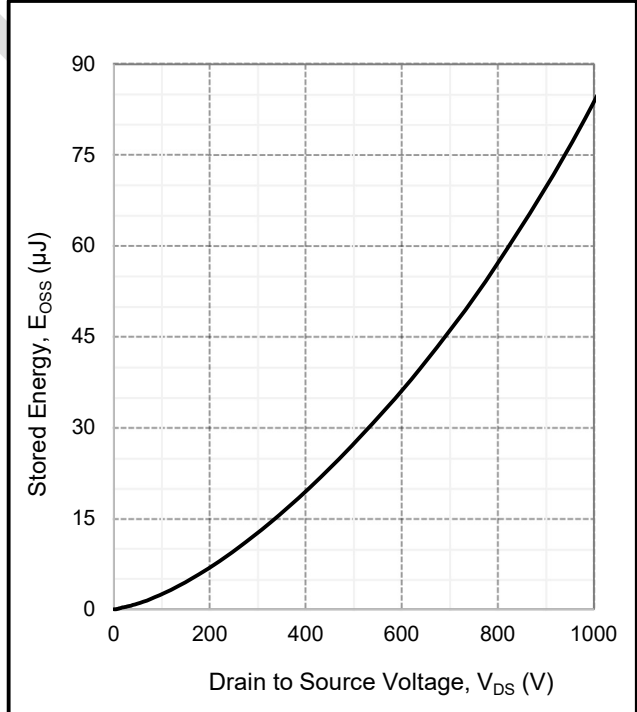


Figure 16. Output capacitor stored energy

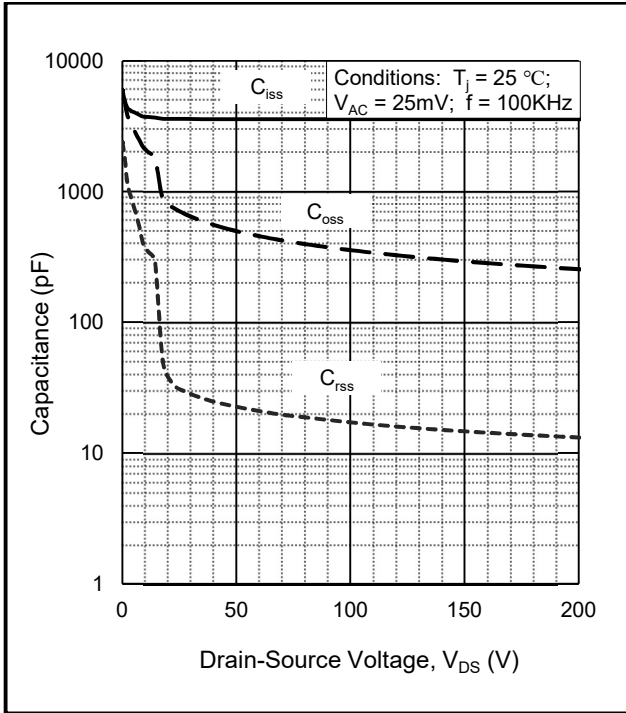


Figure 17. Capacitance vs. drain-source voltage (0 - 200V)

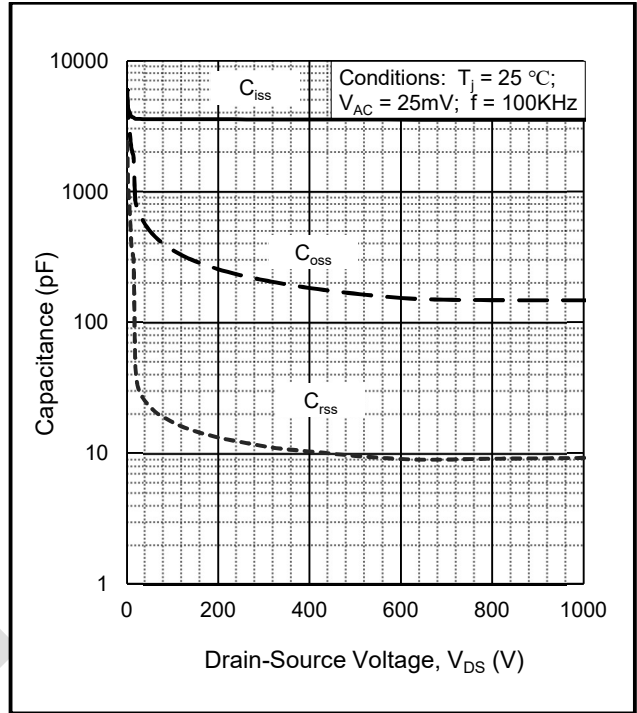


Figure 18. Capacitance vs. drain-source voltage (0 - 1000V)

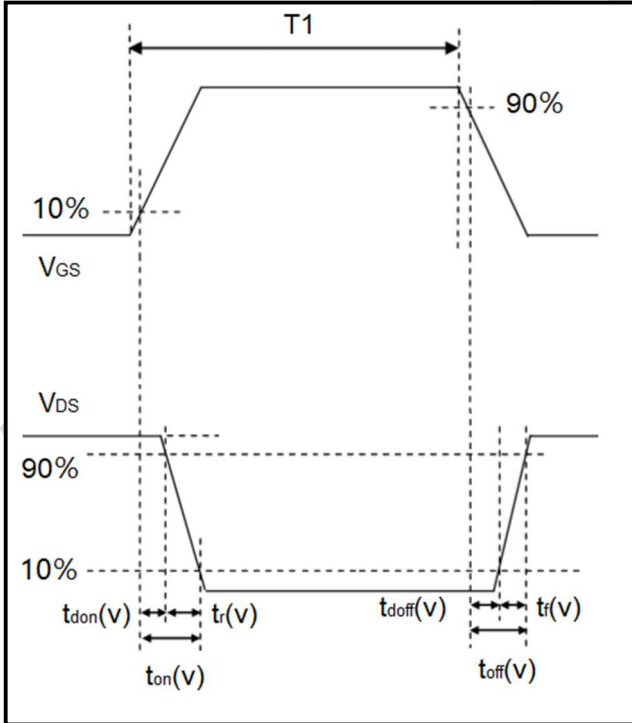


Figure 19. Switching times definition

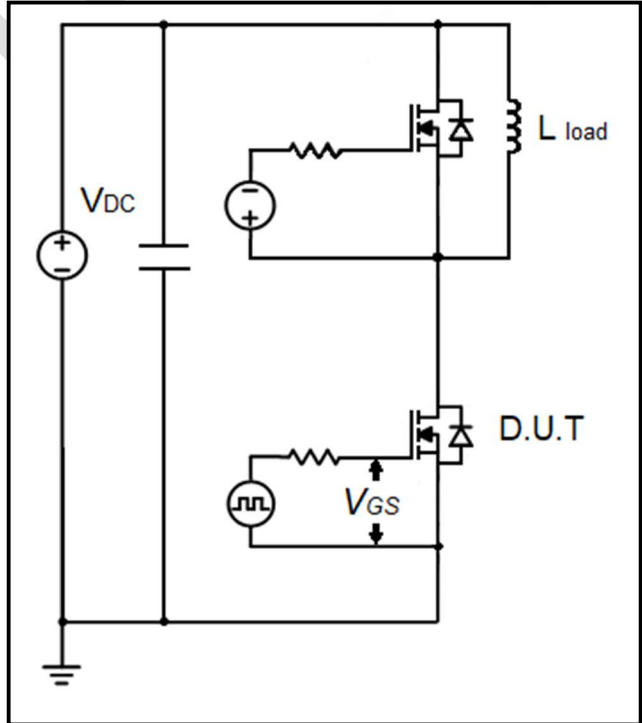


Figure 20. Clamped inductive switching waveform test circuit

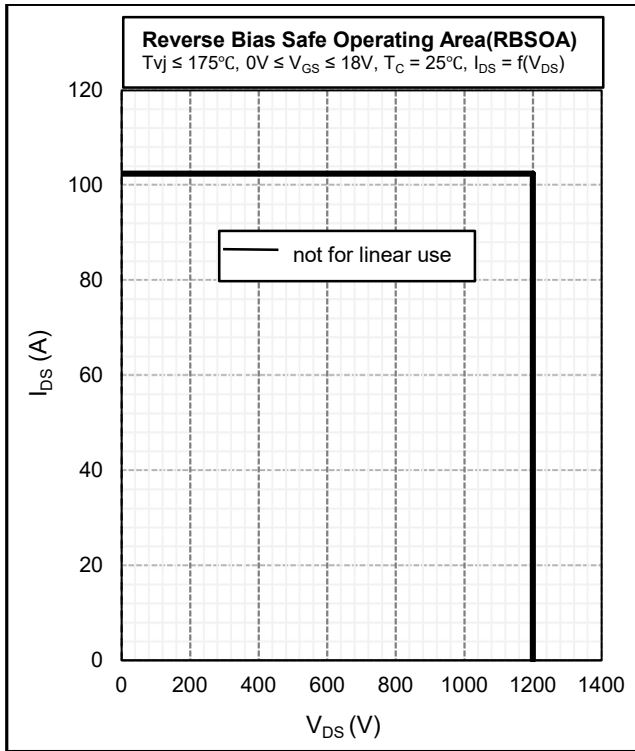
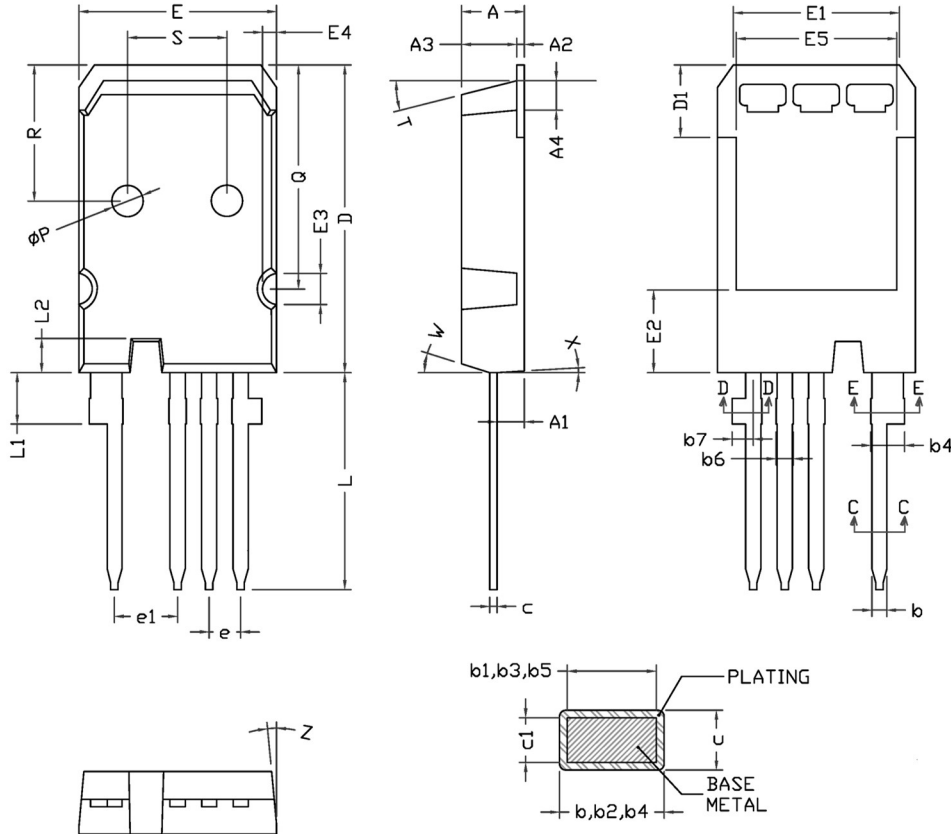


Figure 21. Reverse Bias Safe Operating Area

Package Information:



SECTION C-C, D-D, E-E

AREA	MIN	NOM	MAX
A	4,84	5.03	5.22
Al	2.29	2.39	2.49
A2	0.65	0.70	0.78
A3	4.20	4.33	4.46
A4	2.07	2.20	2.33
D	24,60	24,75	24,85
D1	5,68	5,83	5,98
E	15,71	15,90	16.09
E1	13.22	13.35	13.48
E2	5,93	6,63	7.33
E3	1.82	2.53	3.24
E4	0,81	1.04	1.24
E5	12.37	12,90	13.43
e	2.54 BSC		
e1	5.08 BSC		
L	17.27	17,52	17,77
L1	3,97	4.17	4.37
L2	2.35	2.50	2.65

AREA	MIN	NOM	MAX
b	1.07	-	1.33
b1	1.07	1.20	1.28
b2	2.39	-	2,64
b3	2.39	-	2.69
b4	2.39	-	2,94
b5	2.39	2.53	2.84
b6	1.07	-	1.60
b7	1.30	-	1.70
c	0.65	-	0.78
c1	0,65	0.70	0.75
ΦP	2.40	2.50	2.70
Q	17,77	18.02	18.27
R	10,78	10,98	11.18
S	7,80	8.00	8.20
T	14° REF		
W	21° REF		
X	3° REF		
Z	5° REF		

Ordering Information

Part number	AMR020V120H2i
Package	TO-247-4L (Isolated)
Unit quantity	300 EA
Packing type	Tube

For more information, visit <https://www.apowerc2.com>

Preliminary